ESD Protection Diode Array
Low Capacitance ESD Protection Diode for High Speed Data Line

ESD1014

The ESD1014 surge protectionis designed to protect high speed data lines from ESD, EFT, and lightning.

ON Semiconductor®

LOW CAPACITANCE DIODE SURGE PROTECTION ARRAY

Features

- Low Capacitance (6 pF Maximum Between I/O Lines and GND)
- ESD Rating of Class 3B (Exceeding 8 kV) per Human Body model and Class C (Exceeding 400 V) per Machine Model
- Protection for the Following IEC Standards: IEC 61000−4−2 (ESD) Level 4 − 30 kV (Contact)
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- This is a Pb−Free Device

Typical Applications

- High Speed Communication Line Protection
- USB 1.1 and 2.0 Power and Data Line Protection
- Digital Video Interface (DVI)
- Monitors and Flat Panel Displays
- T1/E1 and T3/E3
- 10/100/1000 Ethernet Protection
- Gigabit Ethernet Protection

PIN CONFIGURATION AND SCHEMATIC

GND (Bottom pad)

I/O	1		10	N/C
N/C	2		9	I/O
I/O	3		8	N/C
N/C	4		7	I/O
VP	5		6	N/C

UDFN10
CASE 517AN

MARKING DIAGRAM


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1014
AYW
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1014 = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
■ = Pb−Free Package

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Power Dissipation (Note 1)	P_{pk}	450	W
Maximum Peak Pulse Current (Note 1)	I_{PP}	30	A
Operating Junction Temperature Range	T_J	−40 to +125	°C
Storage Temperature Range	T_{stg}	−55 to +150	°C
Lead Solder Temperature − Maximum (10 Seconds)	T_L	260	°C
Machine Model (MM) Human Body Model (HBM) IEC 61000−4−2 Contact (ESD)	ESD	0.4 16 30	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
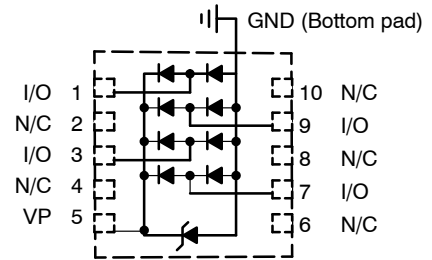1. 8/20 μs Waveform per Figure 2 (@ T_A = 25°C).

ORDERING INFORMATION

Device	Package	Shipping†
ESD1014MUTAG	UDFN10 (Pb−Free)	3000 / Tape & Reel
SZESD1014MUTAG	UDFN10 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

July, 2020 − Rev. 8

ESD1014

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}	(Note 1)			3.3	V
Breakdown Voltage	V_{BR}	I_T=1 mA, (Note 2)	5.0	5.3		V
Reverse Leakage Current	I_R	V_{RWM} = 3.3 V			5.0	μA
Clamping Voltage	V_C	Pin 5 to GND, I_{PP} = 1 A			6.2	V
Clamping Voltage	V_C	Any I/O pin to GND I_{PP} = 1 A I_{PP} = 10 A I_{PP} = 25 A			7.5 9.0 11	V
Maximum Peak Pulse Current	I_{PP}	8/20 μs Waveform per Figure 2			30	A
Junction Capacitance	C_J	V_R = 0 V, f=1 MHz between I/O Pins and GND		3.8	5.0	pF
		V_R = 0 V, f=1 MHz between I/O Pins		1.5	3.0	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
1. Surge protection devices are normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal or greater than the DC or continuous peak operating voltage level.
2. V_{BR} is measured at pulse test current I_T.

TYPICAL PERFORMANCE CURVES

(T_J = 25°C unless otherwise noted)
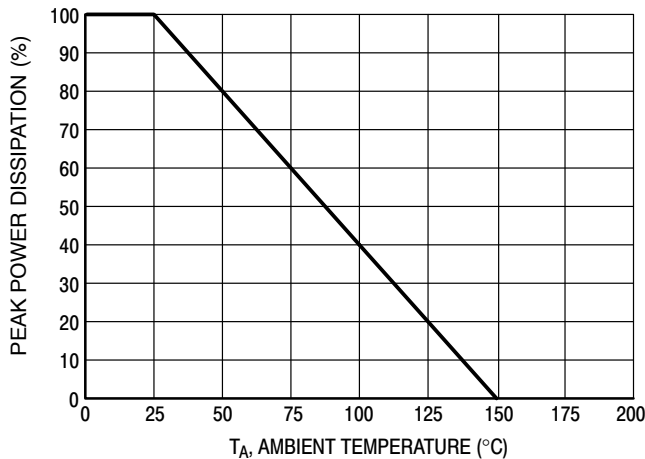
Figure 1. Pulse Derating Curve
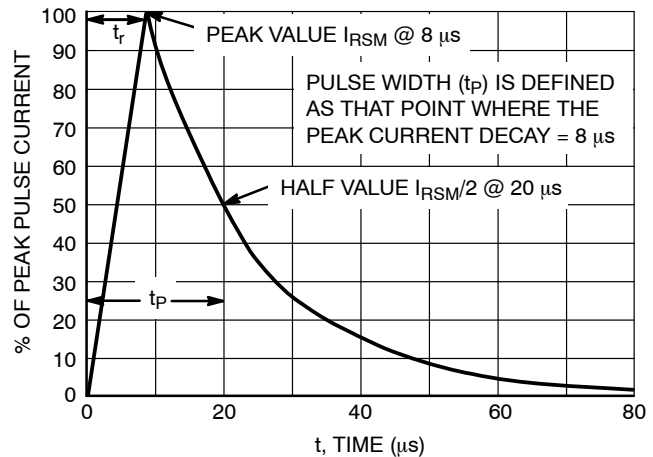
Figure 2. 8/20 μs Pulse Waveform
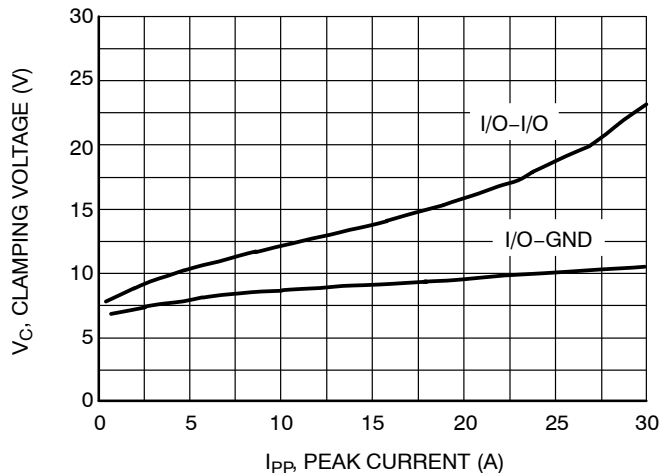
Figure 3. Clamping Voltage, 8/20 μs Waveform
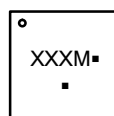
UDFN10 2.6x2.6, 0.5P
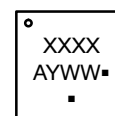CASE 517AN
ISSUE B

SCALE 2:1

DATE 03 OCT 2012
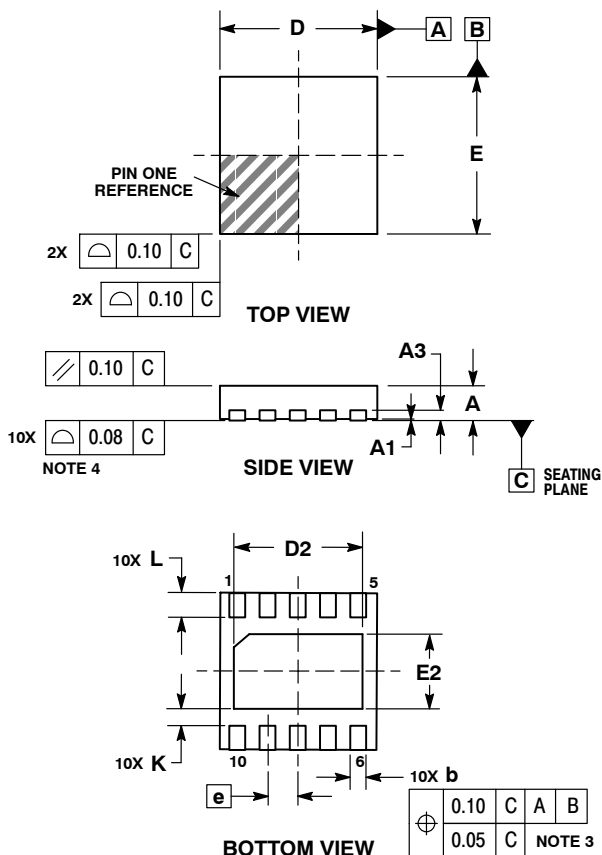
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS MIN	MILLIMETERS MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.20	0.30
D	2.60 BSC	
D2	2.00	2.25
E	2.60 BSC	
E2	1.11	1.36
e	0.50 BSC	
K	0.20	---
L	0.30	0.40

TOP VIEW

2X ⌒ 0.10 C
2X ⌒ 0.10 C

PIN ONE REFERENCE

D
E
A B

SIDE VIEW

⫽ 0.10 C
10X ⌒ 0.08 C
NOTE 4

A3
A
A1
C SEATING PLANE

BOTTOM VIEW

10X L
10X K
D2
E2
e
10X b
1
5
10
6

⊕ 0.10 C A B
0.05 C
NOTE 3

GENERIC MARKING DIAGRAMS*

IC

XXXM▪

XXX = Specific Device Code
M = Month Code
▪ = Pb–Free Package

Discrete

XXXX
AYWW▪

XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb–Free Package

(*Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ▪", may or may not be present.

SOLDERING FOOTPRINT*

2.25
10X 0.58
1.42 2.90
10X 0.30
0.50 PITCH
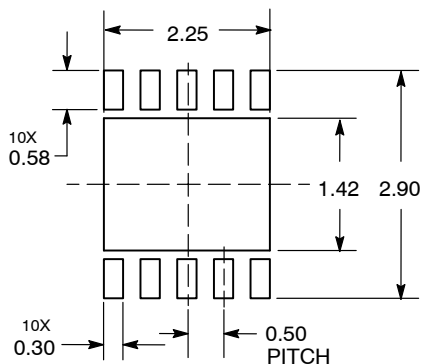
DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN10 2.6X2.6, 0.5P		PAGE 1 OF 1

PUBLICATION ORDERING INFORMATION

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